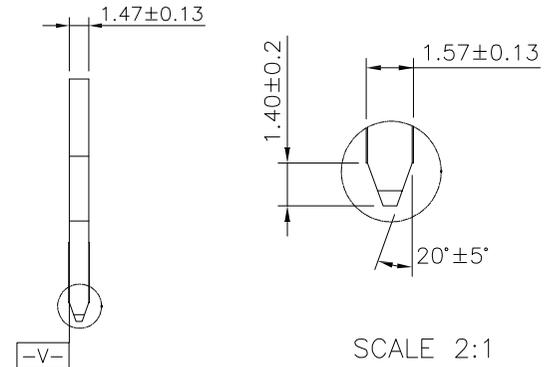
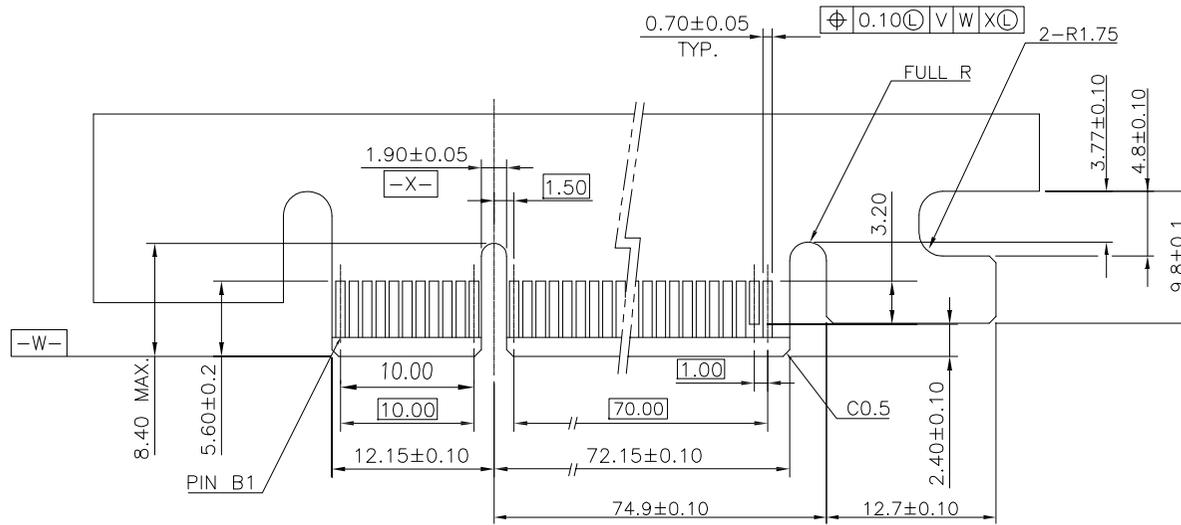


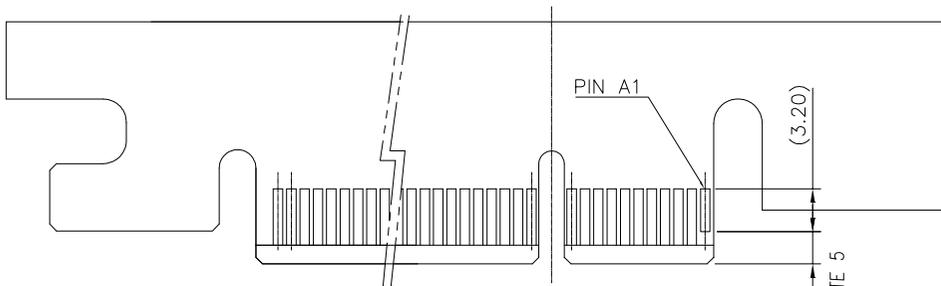
mat'l. code		-		surface		- ✓		tolerance		ASME_Y14.5		projection		product family		PCI_EXPRESS	
lfr		ecn no		dr		date		tolerances unless otherwise specified		MM		title		PCI_EXPRESS_CARD_EDGE_GEN3		5	
B		ELX-DG-25223		LZH		10/26/2016		angles		.0±0.30		scale N/A		INTEGRATE-TYPE_ASS'Y		5	
								±2'		.00±0.20		Amphenol FCI		dwg no		sheet 1 of 4 size	
										.000±0.10				10140055		A4	
														type		CUSTOMER Drawing	
sheet		revision		B													
index		sheet															



SCALE 2:1

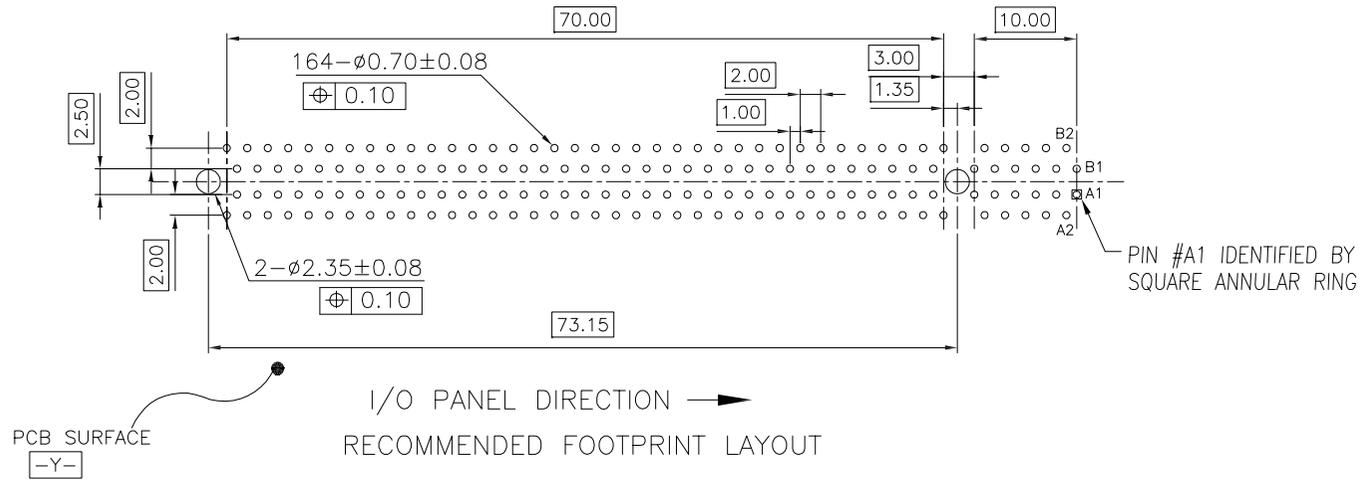
ADD-IN CARD EDGE-FINGER DIMENSIONS

← I/O PANEL DIRECTION
PRIMARY (COMPONENT) SIDE



I/O PANEL DIRECTION →
SECONDARY (SOLDER) SIDE

mat'l. code		surface		tolerance		projection		product family	
-		-		ASME_Y14.5				PCI_EXPRESS	
lfr		ecn no		dr		date		title	
								PCI_EXPRESS_CARD_EDGE_GEN3	
								INTEGRATE-TYPE_ASS'Y	
								dwg no	
								sheet 2 of 4	
								size	
								A4	
								type	
								CUSTOMER Drawing	
sheet index		revision sheet		B					



mat'l. code		-		surface	-	tolerance	ASME_Y14.5	projection	product family	PCI_EXPRESS
lfr	ecn no	dr	date	tolerances unless otherwise specified				MM	title	
				angles	±2'	.02±0.30	.00±0.20		PCI_EXPRESS_CARD_EDGE_GEN3 INTEGRATE-TYPE_ASS'Y	
						.000±0.10		scale	N/A	
		dr	ZHENHUA_LIU	2016-09-18				Amphenol FCI	dwg no	
		enfr	ZHENHUA_LIU	2016-09-18			sheet 3 of 4		size	
		chr	STONE_LI	2016-09-18			10140055		A4	
		appd	PM_ZHENG	2016-09-18			type		CUSTOMER Drawing	
sheet index	revision	B								

NOTES:

1. MATERIAL:

HOUSING: THERMOPLASTIC WITH GLASS FIBER, HALOGEN FREE, UL94V-0.
LATCHES: THERMOPLASTIC WITHOUT GLASS FIBER, HALOGEN FREE, UL94V-0.
CONTACTS: COPPER ALLOY

2. PLATING SPECIFICATION :

CONTACTS AREA: GOLD OVER NICKEL
SOLDER TAIL AREA: MATTE TIN OVER NICKEL

3. WARNING: THE MAXIMUM ALLOWABLE ANGLE TO WITHDRAWAL THE DAUGHTER CARD FROM RETAINER BY 25 DEGREE.

4. PRODUCT SPECIFICATION: GS-12-233.

PACKAGING SPECIFICATION: GS-14-992.

5. NO TIE BAR PERMITTED FOR CARD EDGE TO LEADING EDGE OF PAD FOR PINS "A1" AND "B81."

6. CHAMFER EDGE MUST BE FREE OF CUTTING BURRS.

7. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004.

8. ALL HOLE DIAMETERS ARE FINISHED HOLE SIZES.

9. THE HOUSING WILL WITHSTAND EXPOSURE TO 260C° PEAK TEMPERATURE FOR 5 SECONDS IN WAVE SOLDER APPLICATION WITH 1.46MM MINIMUM THICK CIRCUIT BOARD .

PRODUCT NUMBER CODE

10140055 -x x x x x x LF

HOUSING COLOR OPTIONS

1-BLACK FOR BASE & RM

PEGS OPTIONS

1-PLASTIC POST

TERMINAL PLATING OPTIONS

0-50u" Ni UNDERPLATE
30u" Au CONTACT AREA
100u" TIN TAIL AREA
1-50u" Ni UNDERPLATE
15u" Au CONTACT AREA
100u" TIN TAIL AREA
2-50u" Ni UNDERPLATE
GOLD FLASH CONTACT AREA
100u" TIN TAIL AREA

APPLICATIONS

LF- LEAD FREE

PACKAGING OPTIONS

T-TRAY PACKAGING

POS OPTIONS

3-164

TAIL LENGTH OPTION (DIM. A)

1- 3.10mm
2- 2.30mm

mat'l. code		surface		tolerance		projection		product family	
-		-		ASME_Y14.5				PCI_EXPRESS	
lfr	ecn no	dr	date	tolerances unless otherwise specified		MM		title	
				angles	lineal	← MM →		PCI_EXPRESS_CARD_EDGE_GEN3	
				±2'	±.00±.0.20	scale N/A		INTEGRATE-TYPE_ASS'Y	
					±.000±.0.10			sheet 4 of 4 size	
		dr	ZHENHUA_LIU	2016-09-18			dwg no		
		enfr	ZHENHUA_LIU	2016-09-18			10140055		A4
		chr	STONE_LI	2016-09-18					
		appd	PM_ZHENG	2016-09-18			CUSTOMER Drawing		
sheet index	revision sheet	B							